ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH WARP-FREE CHIP

An integrated circuit package system includes: providing an integrated circuit wafer having an active side and a backside; forming a stress-relieving layer on the backside; forming an adhesion layer on the stress-relieving layer; dicing the integrated circuit wafer into a semiconductor chip with the stress-relieving layer and the adhesion layer on the backside of the semiconductor chip; and mounting the semiconductor chip over electrical interconnects. (Fig. 1)